SDAS205A – APRIL 1982 – REVISED DECEMBER 1994

- 8-Line to 1-Line Multiplexers Can Perform as:
 - Boolean Function Generators Parallel-to-Serial Converters Data Source Selectors
- Input Clamping Diodes Simplify System Design
- Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

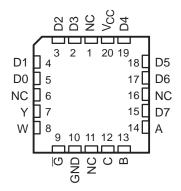
description

These data selectors/multiplexers provide full binary decoding to select one-of-eight data sources. The strobe (\overline{G}) input must be at a low logic level to enable the inputs. A high level at the strobe terminal forces the W output high and the Y output low.

The SN54ALS151 is characterized for operation over the full military temperature range of -55° C to 125°C. The SN74ALS151 and SN74AS151 are characterized for operation from 0°C to 70°C.

SN54ALS151 J PACKAGE SN74ALS151, SN74AS151 D OR N PACKAGE (TOP VIEW)									
D3 [D2 [D1 [D0 [Y [G] GND [1 2 3 4 5 6 7 8	14 13 12 11 10	V _{CC} D4 D5 D6 D7 A B C						

SN54ALS151 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

	IN	PUTS								
	SELECT	STROBE	OUTPUTS							
С	В	Α	G	Y	W					
Х	Х	Х	Н	L	Н					
L	L	L	L	D0	D0					
L	L	Н	L	D1	D1					
L	н	L	L	D2	D2					
L	н	Н	L	D3	D3					
Н	L	L	L	D4	D4					
Н	L	Н	L	D5	D5					
Н	Н	L	L	D6	D6					
н	Н	Н	L	D7	D7					

FUNCTION TABLE

H = high level, L = low level, X = irrelevant

D0, D1, . . . D7 = the level of the respective D input

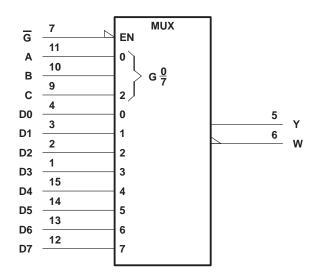
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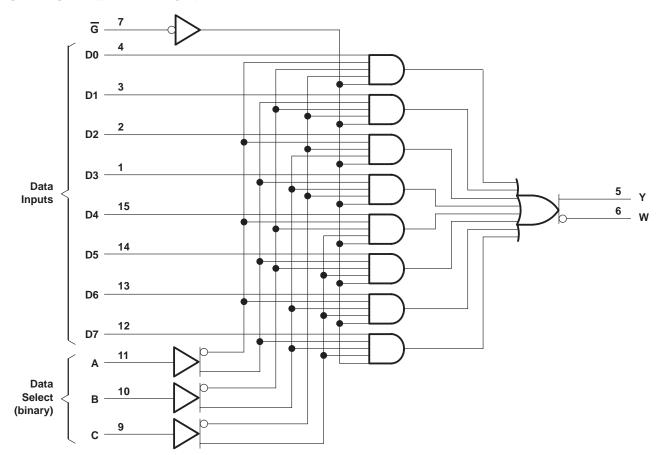
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logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, J, and N packages.

logic diagram (positive logic)



Pin numbers shown are for the D, J, and N packages.



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V _{CC} Input voltage, V _I	
Operating free-air temperature range, TA: SN54ALS151	–55°C to 125°C
SN74ALS151	0°C to 70°C
Storage temperature range	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN	SN54ALS151		SN74ALS151			
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.7			0.8	V
ЮН	High-level output current			-1			-2.6	mA
IOL	Low-level output current			12			24	mA
Т _А	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	7507.0	TEST CONDITIONS		54ALS1	51	SN				
PARAMETER	TEST C	ONDITIONS	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT	
VIK	V _{CC} = 4.5 V,	l _l = – 18 mA			-1.5			-1.5	V	
	V_{CC} = 4.5 V to 5.5 V,	$I_{OH} = -0.4 \text{ mA}$	V _{CC} -2	2		V _{CC} -2	2			
VOH	V _{CC} = 4.5 V	$I_{OH} = -1 \text{ mA}$	2.4	3.3					V	
		$I_{OH} = -2.6 \text{ mA}$				2.4	3.2			
Max		I _{OL} = 12 mA		0.25	0.4		0.25	0.4	v	
VOL	$V_{CC} = 4.5 V$	I _{OL} = 24 mA					0.35	0.5	V	
lį	V _{CC} = 5.5 V,	$V_{I} = 7 V$			0.1			0.1	mA	
IIН	V _{CC} = 5.5 V,	V _I = 2.7 V			20			20	μΑ	
١ _{١L}	V _{CC} = 5.5 V,	V _I = 0.4 V			-0.1			-0.1	mA	
۱ ₀ §	V _{CC} = 5.5 V,	V _O = 2.25 V	-20		-112	-30		-112	mA	
Icc	V _{CC} = 5.5 V,	Inputs at 4.5 V		7.5	12		7.5	12	mA	

[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

§ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.



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switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	VC CL RL TA	UNIT			
		(001101)	SN54A	LS151	SN74A	LS151	
			MIN	MAX	MIN	MAX	
tPLH		Y	4	21	4	18	
^t PHL	A, B, or C	ř	7	35	8	24	ns
^t PLH		W	5	36	7	24	
^t PHL	A, B, or C	VV	7	26	7	23	ns
^t PLH	Any D	V	3	14	3	10	~~
^t PHL	Any D	Y	5	21	5	15	ns
^t PLH	Anu D	W	3	23	3	15	
^t PHL	Any D	VV	4	20	4	15	ns
tPLH	ы	Y	4	21	4	18	
^t PHL	G	ř	4	25	4	19	ns
^t PLH	G	W	5	27	5	19	ns
^t PHL	6	۷V	5	26	5	23	115

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[‡]

Supply voltage, V _{CC}	
Input voltage, V _I	
Operating free-air temperature range, T _A : SN74AS151	0°C to 70°C
Storage temperature range	. −65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN	SN74AS151		
		MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	V
VIH	High-level input voltage	2			V
VIL	Low-level input voltage			0.8	V
ЮН	High-level output current			-15	mA
IOL	Low-level output current			48	mA
Т _А	Operating free-air temperature	0		70	°C



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			TEST CONDITIONS				
		TEST CON					UNIT
VIK		V _{CC} = 4.5 V,	lj = – 18 mA			-1.2	V
N		V_{CC} = 4.5 V to 5.5 V,	$I_{OH} = -2 \text{ mA}$	V _{CC} -2			
VOH	Γ	$V_{CC} = 4.5 V,$	I _{OH} = – 15 mA	2.4	3.2		V
VOL		$V_{CC} = 4.5 V,$	I _{OL} = 48 mA		0.35	0.5	V
	A, B, or C					0.2	
ų	All others	$V_{CC} = 5.5 V,$	V _I = 7 V			0.1	mA
	A, B, or C					40	
ΙΗ	All others	V _{CC} = 5.5 V,	V _I = 2.7 V			20	μA
	A, B, or C					-1	
ΊL	All others $V_{CC} = 5.5 \text{ V}, \qquad V_{I} = 0.4 \text{ V}$		$V_{I} = 0.4 V$			-0.5	mA
10‡		V _{CC} = 5.5 V,	V _O = 2.25 V	-30		-112	mA
ICC		V _{CC} = 5.5 V			18.6	30	mA

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[‡] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

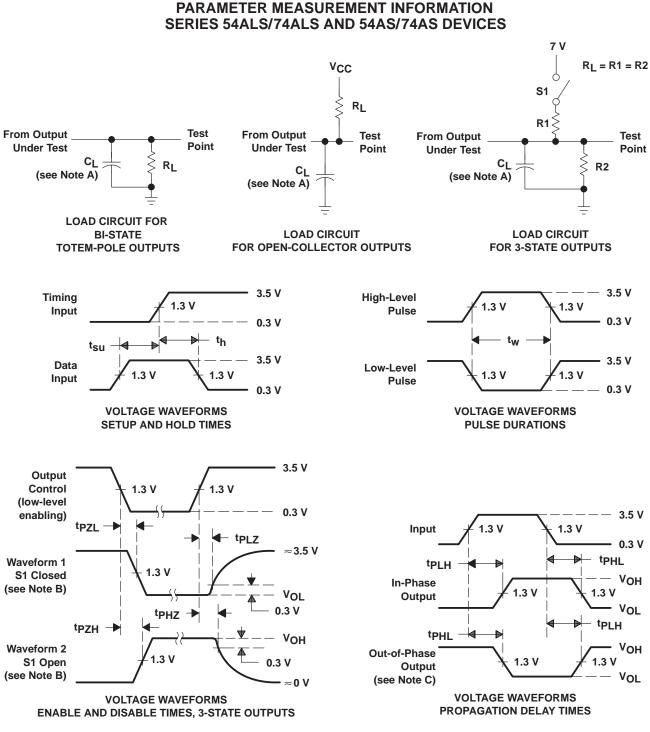
switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4.5 V \text{ to } 5.5 V,$ $C_{L} = 50 \text{ pF},$ $R_{L} = 500 \Omega,$ $T_{A} = \text{MIN to MAX}$ $SN74AS151$		UNIT
			MIN	MAX	
^t PLH	A, B, or C	Y	4.5	14.5	
^t PHL	А, В, ОГС	Ţ	4.5	15	ns
^t PLH	A, B, or C	14/	4	12	ns
^t PHL	A, B, of C	W	4	12	
^t PLH	A see D	N N	3	10.5	
^t PHL	Any D	Y	3	11	ns
^t PLH	And D	14/	2	6.5	
^t PHL	Any D	W	1	4.5	ns
^t PLH	G		4.5	14	
^t PHL	G	Y	3	11	ns
^t PLH	G	W	1.5	6	
^t PHL	5	٧V	3	10	ns

§ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



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NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: PRR \leq 1 MHz, t_{f} = t_{f} = 2 ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms



TEXAS INSTRUMENTS www.ti.com

18-Sep-2008

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Packag Qty	e Eco Plan ⁽²⁾	Lead/Ball Finisł	MSL Peak Temp ⁽³⁾
84141012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
8414101EA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
8414101FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SN54ALS151J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN74ALS151D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS151DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS151DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS151DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS151DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS151DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS151N	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS151N3	OBSOLETE	PDIP	Ν	16		TBD	Call TI	Call TI
SN74ALS151NE4	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS151NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS151NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS151NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS151D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS151DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS151DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS151DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS151DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS151DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS151N	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AS151NE4	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AS151NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS151NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS151NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

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Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SNJ54ALS151FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54ALS151J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54ALS151W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS151DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74ALS151NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74AS151DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74AS151NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1



PACKAGE MATERIALS INFORMATION

19-Mar-2008



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS151DR	SOIC	D	16	2500	333.2	345.9	28.6
SN74ALS151NSR	SO	NS	16	2000	346.0	346.0	33.0
SN74AS151DR	SOIC	D	16	2500	333.2	345.9	28.6
SN74AS151NSR	SO	NS	16	2000	346.0	346.0	33.0

MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0-10 Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



MLCC006B - OCTOBER 1996

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC



D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AC.



D(R-PDSO-G16)



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Refer to IPC7351 for alternate board design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



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